

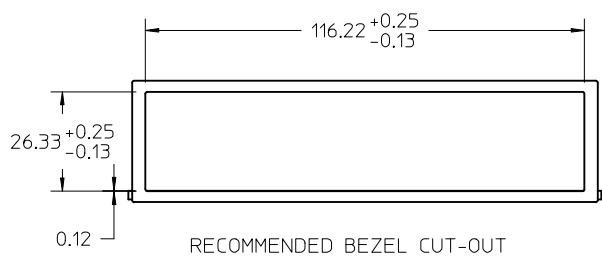
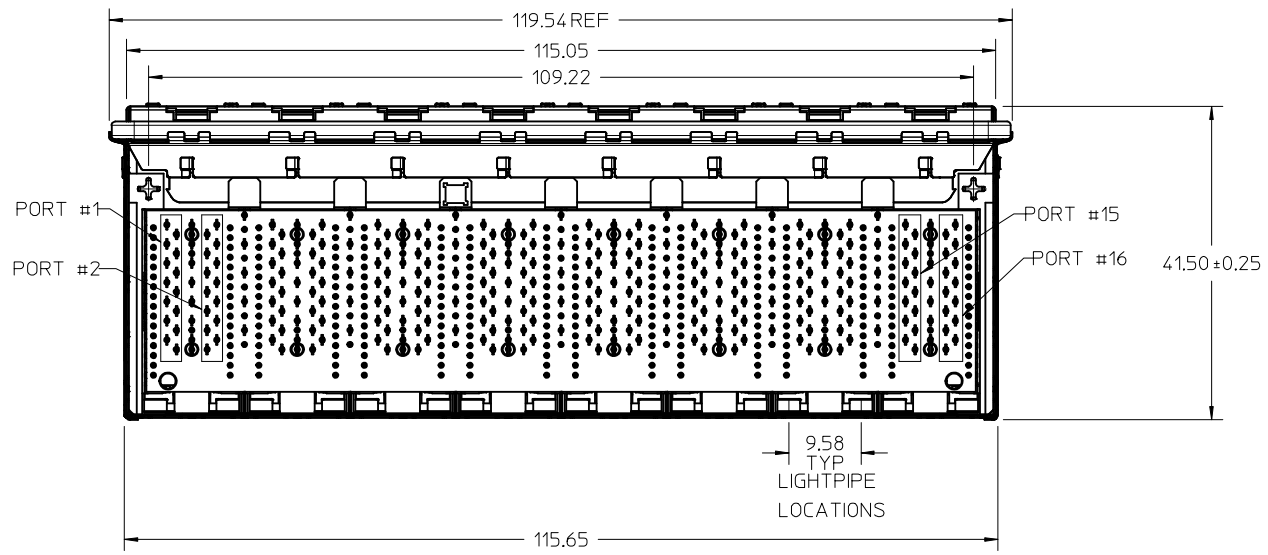
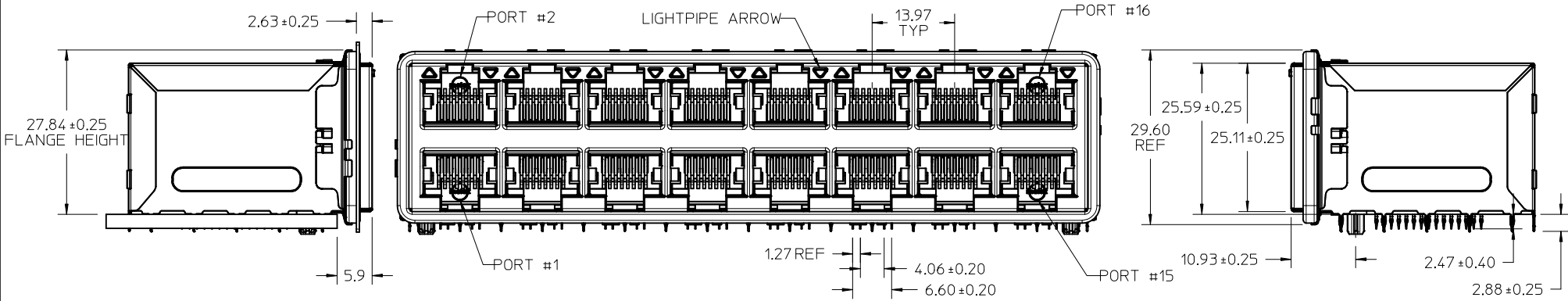
ELECTRICAL CHARACTERISTIC		VALUE AT 25°C
CHIP SIDE RETURN LOSS	1 - 50 MHz	30 dB MIN
	50 - 100 MHz	$30-0.04*(\text{freq}(\text{MHz})-50)$ dB MIN
	100 - 200 MHz	$28-0.10*(\text{freq}(\text{MHz})-100)$ dB MIN
	200 - 400 MHz	$18-0.04*(\text{freq}(\text{MHz})-200)$ dB MIN
	400 - 500 MHz	$10-0.01*(\text{freq}(\text{MHz})-400)$ dB MIN
LINE SIDE RETURN LOSS	1 - 50 MHz	30 dB MIN
	50 - 100 MHz	$30-0.04*(\text{freq}(\text{MHz})-50)$ dB MIN
	100 - 200 MHz	$28-0.10*(\text{freq}(\text{MHz})-100)$ dB MIN
	200 - 400 MHz	$18-0.04*(\text{freq}(\text{MHz})-200)$ dB MIN
	400 - 500 MHz	$10-0.01*(\text{freq}(\text{MHz})-400)$ dB MIN
INSERTION LOSS	1 - 400 MHz	3 dB MAX
MODE CONVERSION CM ON LINE TO DM ON CHIP	1 - 50 MHz	-48 dB MAX
	50 - 100 MHz	$-48+0.1*(\text{freq}(\text{MHz})-50)$ dB MAX
	100 - 500 MHz	$-43+0.03*(\text{freq}(\text{MHz})-100)$ dB MAX
MODE CONVERSION CM ON LINE TO DM ON CHIP	1 - 50 MHz	-38 dB MAX
	50 - 100 MHz	$-38+0.1*(\text{freq}(\text{MHz})-50)$ dB MAX
	100 - 200 MHz	$-33+0.03*(\text{freq}(\text{MHz})-100)$ dB MAX
	200 - 300 MHz	$-30+0.02*(\text{freq}(\text{MHz})-200)$ dB MAX
	300 - 500 MHz	$-28+0.01*(\text{freq}(\text{MHz})-300)$ dB MAX
COMMON MODE REJECTION	1 - 100 MHz	-23 dB MAX
	100 - 400 MHz	$-23+0.02*(\text{freq}(\text{MHz})-100)$ dB MAX
	400 - 500 MHz	$-17+0.01*(\text{freq}(\text{MHz})-400)$ dB MAX
ALIEN CROSSTALK	1 - 50 MHz	-70 dB MAX
	50 - 200 MHz	$-70+0.047*(\text{freq}(\text{MHz})-50)$ dB MAX
	200 - 400 MHz	$-63+0.015*(\text{freq}(\text{MHz})-200)$ dB MAX
	400 - 500 MHz	$-60+0.03*(\text{freq}(\text{MHz})-400)$ dB MAX
CROSSTALK WITHIN A PORT	1 - 50 MHz	-40dB MAX
	50 - 100 MHz	$0.12*(\text{freq}(\text{MHz})-50)-40$ dB MAX
	100 - 200 MHz	$0.06*(\text{freq}(\text{MHz})-100)-34$ dB MAX
	200 - 300 MHz	$0.03*(\text{freq}(\text{MHz})-200)-28$ dB MAX
	300 - 500 MHz	$0.015*(\text{freq}(\text{MHz})-300)-25$ dB MAX
OCL	100kHz / 0.1V	100 nH MIN
TURN RATIO		1.00±0.02
INSULATION RESISTANCE		2250 VDC

NOTES:

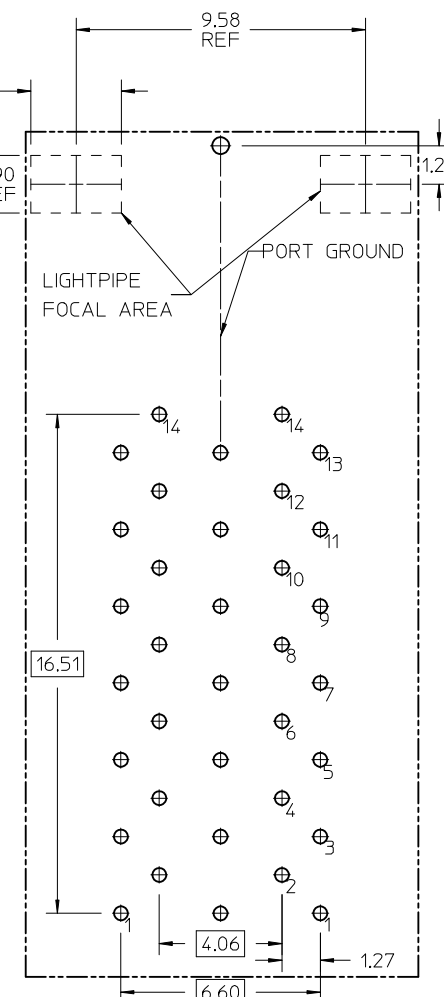
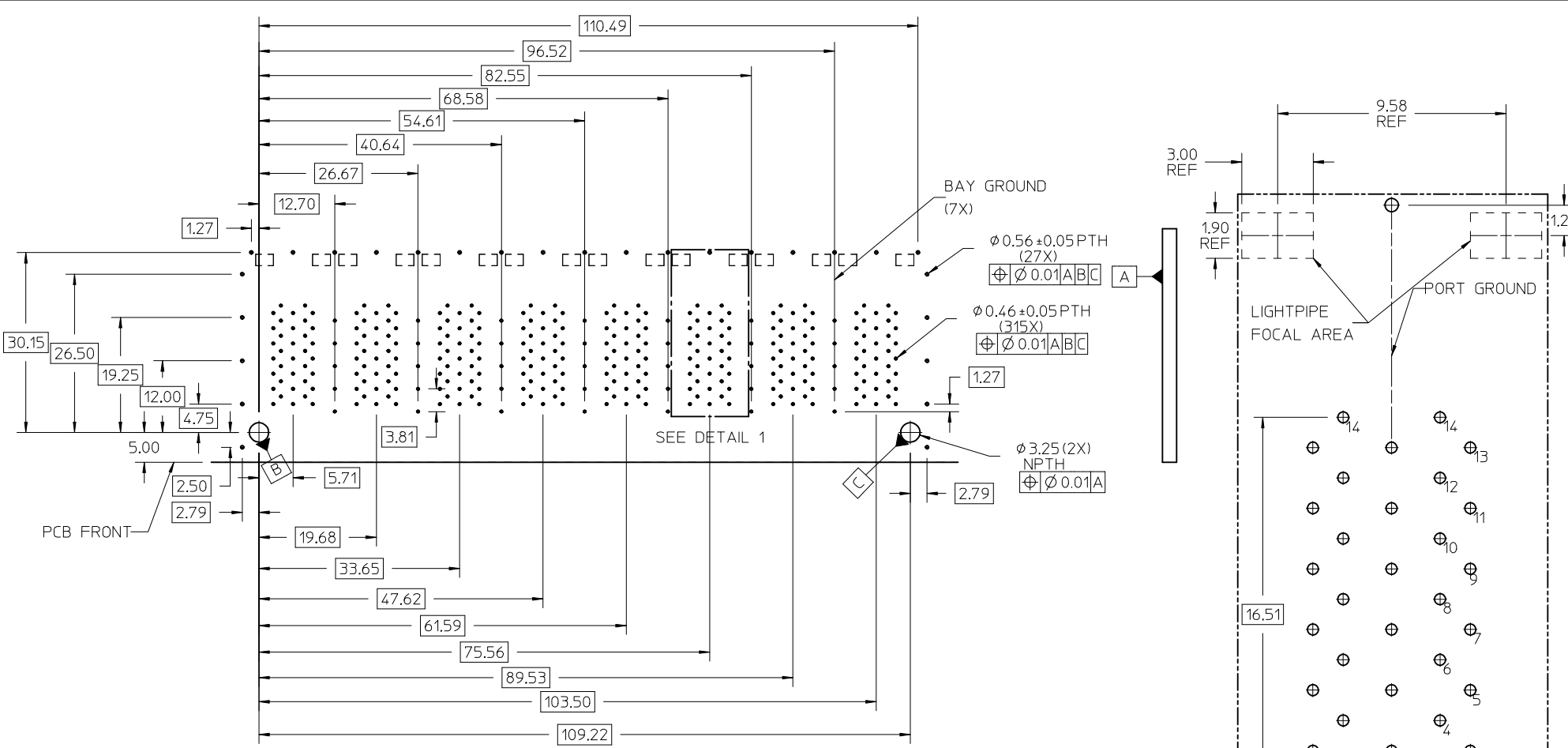
- MATERIAL:
 - HOUSING: LCP, GLASS FILLED, UL94V-0, COLOR: BLACK
 - CONTACT BEAMS: COPPER ALLOY
 - SHIELD: BRASS
 - GASKET FLANGE: STAINLESS STEEL
 - EMI GASKET: CONDUCTIVE MATERIAL OVER ELASTOMERIC SILICONE CORE
 - PCB PINS: COPPER ALLOY
- PLATING:
 - CONTACT BEAMS: 50 MICROINCHES MIN. GOLD AND OVER
150 MICROINCHES MIN NICKEL UNDERPLATE
 - SHIELD: NICKEL OVERALL
- PRODUCT SPECIFICATION: PS-170711-0001
- APPLICATION SPECIFICATION: AS-170711-0001
- PRODUCT TO BE TRAY PACKAGED PER PACKAGING SPECIFICATION: PK-170849-0001.
- CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- MOLEX LOGO, PART NUMBER, AND DATE CODE TO BE LOCATED IN THIS APPROXIMATE LOCATION. FOUR DIGIT DATE CODE TO BE THE 3 DIGIT JULIAN DAY AND 1 DIGIT YEAR (EXAMPLE: 0337 IS FEBRUARY 2, 2007)
- SHIELD SURFACE FINISHES (CLASS A, B OR C) COMPLY WITH THE REQUIREMENTS FOR VISUAL ACCEPTANCE PER COSMETIC SPECIFICATION ES-46030-006.

MAT'L NO.	LIGHT PIPE
170722-0008	YES
N/A	NO

UPDATE OF VIA QTY EC NO: UCP2013-0194 DRWN:BWIRKUS 2012/07/16 CHKD: APPR:KLANG 2012/07/17 REV:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY DATE BJANOWIAK 2011/07/29	TITLE	10GBE 2X8 STACKED (P/F) NO CMS-LP 5AA21B00 MOLEX INCORPORATED SD-170722-0008	
	▽=0	4 PLACES ± --- ± ---	CHECKED BY DATE TMCCLELLAND 2012/05/04			
	▽=0	2 PLACES ±0.13 ± ---	1 PLACE ±0.25 ± ---	APPROVED BY DATE TMCCLELL 2011/07/30		SHEET NO. 1 OF 3
		ANGULAR ±1/2°	MATERIAL NO. SEE CHART	DOCUMENT NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE C			



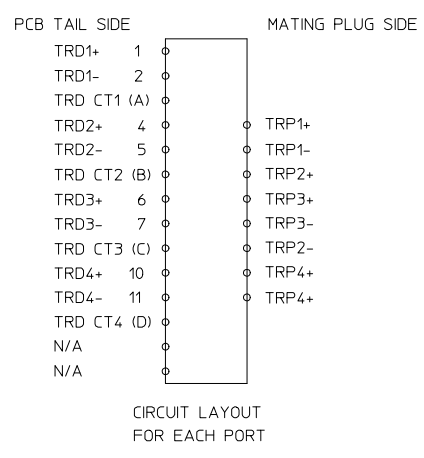
SEE SHEET 1 EC NO: UCP2013-0194 DRAWN BY: DRWINBWRKUS 2012/07/16 CHKD: APPR: KLANG 2012/07/17 REV: A	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	▽=0	mm	INCH	DRAWN BY	DATE	TITLE 10GbE 2X8 STACKED (P/F) NO CMS-LP 5AA21B00 molex			
	▽=0	4 PLACES ± ---	± ---	BJANOWIAK	2011/07/29				
	▽=0	3 PLACES ± ---	± ---	CHECKED BY	DATE	DOCUMENT NO. SD-170722-0008			
▽=0	2 PLACES ± 0.13	± ---	TMCCLELLAND	2012/05/04					
	1 PLACE ± 0.25	± ---	APPROVED BY	DATE	SHEET NO. 2 OF 3				
	0 PLACE ±	±	TMCCLELL	2011/07/30					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ±1/2°		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



RECOMMENDED PCB LAYOUT
COMPONENT SIDE

DETAIL 1
SCALE 8:1

PIN #1	TRD1+
PIN #2	TRD1-
PIN #3	TRD CT1
PIN #4	TRD2+
PIN #5	TRD2-
PIN #6	TRD CT2
PIN #7	TRD3+
PIN #8	TRD3-
PIN #9	TRD CT3
PIN #10	TRD4+
PIN #11	TRD4-
PIN #12	TRD CT4
PIN #13	N/A
PIN #14	N/A



SEE SHEET 1 EC NO: UCP2013-0194 DRAWN: BWRKUS 2012/07/16 CHKD: APPR: KLANG 2012/07/17 REV: A	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE BJANOWIAK 2011/07/29	10GBE 2X8 STACKED (P/F) NO CMS-LP 5AA21B00 molex		
	▽=0	3 PLACES ± --- ± ---	CHECKED BY DATE TMCCLELLAND 2012/05/04			
	▽=0	2 PLACES ± 0.13 ± ---	APPROVED BY DATE TMCCLELL 2011/07/30	MATERIAL NO. SD-170722-0008 SHEET NO. 3 OF 3		
	0 PLACE ± ±	ANGULAR ±1/2°	SEE SHEET 1 DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
SIZE C THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						